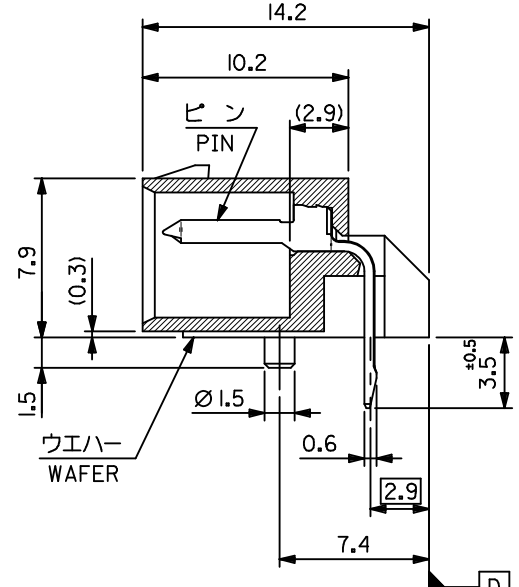
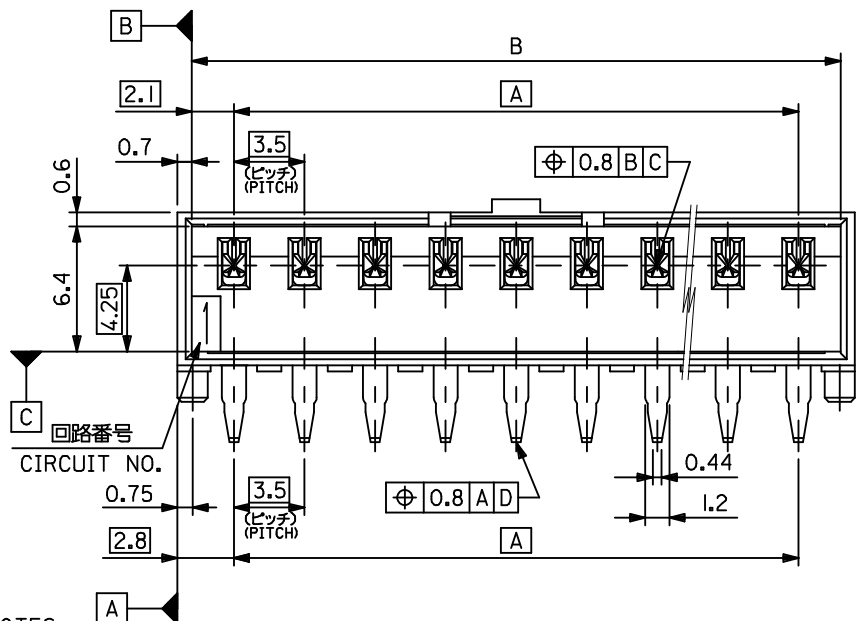


基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



8.7	54.6	53.2	49.0	53259-1520	15
				-1510	
	51.1	49.7	45.5	-1420	14
				-1410	
	47.6	46.2	42.0	-1320	13
				-1310	
	44.1	42.7	38.5	-1220	12
				-1210	
	40.6	39.2	35.0	-1120	11
				-1110	
	37.1	35.7	31.5	-1020	10
				-1010	
	33.6	32.2	28.0	-0920	9
				-0910	
	30.1	28.7	24.5	-0820	8
				-0810	
	26.6	25.2	21.0	-0720	7
				-0710	
	23.1	21.7	17.5	-0620	6
				-0610	
	19.6	18.2	14.0	-0520	5
				-0510	
8.7	16.1	14.7	10.5	-0420	4
				-0410	
6.1	12.6	11.2	7.0	-0320	3
				-0310	
6.1	9.1	7.7	3.5	-0220	2
				53259-0210	
(D)	C	B	A	ENG. NO.	CKT. 種別

注記 NOTES

1. 嵌合相手 : 51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質 MATERIAL
ウエハー : PBTP (ガラス15%入り)、UL94V-0
WAFER : PBTP (G.F 15%), UL94V-0
ピン : 53259-***10 [リン青銅、半田メッキ (t=0.254)]
PIN : [PHOS. BRO., SOLDER PLATED (t=0.254)]
53259-***20 [黄銅、半田メッキ (t=0.254)]
[BRASS, SOLDER PLATED (t=0.254)]

REVISED EC NO: J2014-1003 DRWN:TYAJIMA01 2013/12/25 CHKD:KASAKAWA 2013/12/25 APPR:NUKITA 2014/01/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TYAJIMA01	DATE 2013/12/25	TITLE 3.5 W/B CONN WAFER ASSY R/A		
	10 OVER 30 UNDER	±0.25	CHECKED BY KASAKAWA	DATE 2013/12/25			
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2014/01/07			
ANGULAR	±3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-53259-006	SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					